

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

5 Claim 1 (Currently amended): A ~~Multiple-chips~~multi-chip image sensor module, comprising:

a first substrate, which has an upper surface and a lower surface, wherein the upper surface is formed with a plurality of first ~~connected~~connecting ends, and the lower surface is formed with a plurality of second ~~connected~~connecting ends; □

10 a photosensitive chip, which is arranged at-on the upper surface of the first substrate, and electrically connected to the first ~~connected~~connecting ends by a plurality of first wires; □

15 a lens holder formed with a ~~penetrate-hole~~through hole at a center ~~central~~ thereof, wherein an internal thread ~~being-is~~ formed on an ~~the~~ inner wall of the ~~penetrate-hole~~through hole, and the lens holder ~~being-is~~ mounted on the upper surface of the first substrate to encapsulate the photosensitive chip; □

20 a lens barrel arranged within the ~~penetrate-hole~~through hole of the lens holder and ~~is~~ formed with an external thread, which is screwed to the internal thread of the lens holder, wherein the lens barrel is ~~being~~ formed with a chamber and an opening communicating with the chamber; □

an aspheric lens and a transparent layer placed within the chamber; □

25 a second substrate having ~~formed with~~ a first surface on which a plurality of signal output ends are formed, and a second surface on which a plurality of signal input ends are formed, wherein the first surface of the second substrate is mounted on the lower surface of the first substrate, and ~~surface~~, then the signal output ends are electrically connected the second connecting ends of the first substrate; and ~~surface~~ □ and

30 a lower chip located on the second surface of the second substrate and is electrically connected to the signal input ends of the second substrate.

Claim 2 (Currently amended): The ~~multiple-chips~~multi-chip image sensor

module according to claim 1, wherein the second substrate is a flexible/hard combination board, which includes a flexible board and a hard board, the lower chip is mounted on the flexible board, and the hard board is mounted on the lower surface of the first substrate.

5        Claim 3 (Currently amended): The ~~multiple-chips~~ multi-chip image sensor module according to claim 1, wherein the lower chip is electrically connected to the signal input ends by second wires.

         Claim 4 (Currently amended): The ~~multiple-chips~~ multi-chip image sensor module according to claim 1, ~~wherein further includes a expose~~ further comprising  
10    a resin layer for encapsulating the lower chip.

         Claim 5 (Currently amended): The ~~multiple-chips~~ multi-chip image sensor module according to claim 1, wherein the lower chip is a signal processor digit ~~and the image sensor module further comprises~~ ~~further includes a expose a~~ resin layer for encapsulating the lower chip.

15